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ABSTRACT OF THE DISCLOSURE

A copper-clad laminate is composed of a polyimide film and an electrolytically plated copper film placed on at least one surface side of the polyimide film, in which the copper film has at most 200 protrusions having a diameter of 15 μ m or more on its surface not facing the polyimide film, and the laminate has a peel strength of 1 kgf/cm or more and shows a peel strength of 0.6 kgf/cm or more after heating at 150°C for 24 hours.